

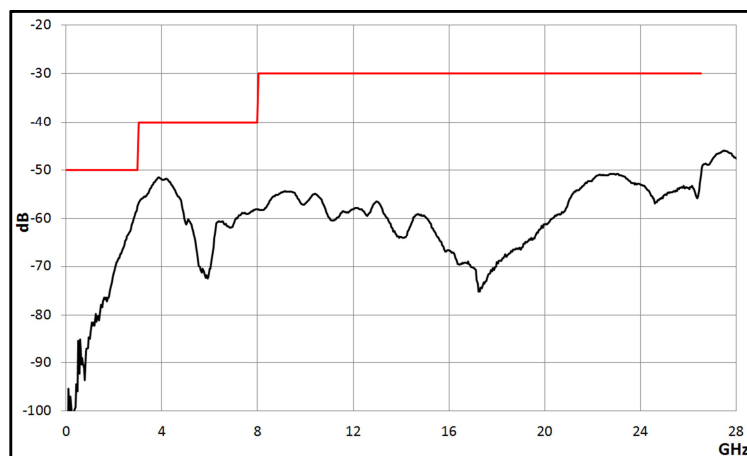
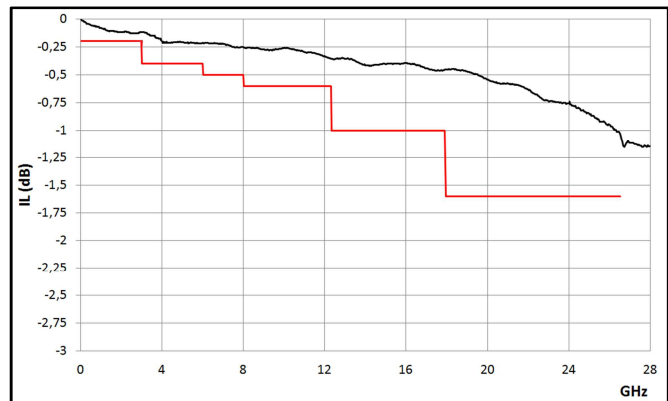
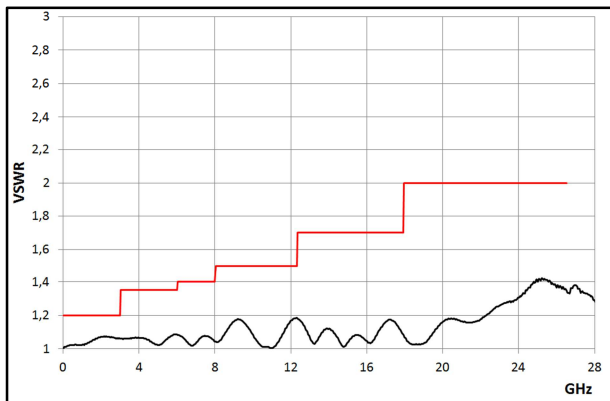
RF PERFORMANCES (1)

Frequency Range (GHz)		V.S.W.R	IL	Isolation (min) dB		Average power W	Third order Inter modulation	Impedance
		(max)	(max) dB	switch alone	switch+board layout (1)	hot switching		Ohms
DC – 8 DC – 18 DC – 26.5	DC – 3	1.20	0.20	50	50	40	-110 dBc Typical @ 1730 MHz (2 carriers 20W)	50
	3 – 6	1.35	0.40	40	40	25		
	6 – 8	1.40	0.50	40	40	5		
	8 – 12.4	1.50	0.60	40	30	3		
	12.4 – 18	1.70	1.00	40	30	1		
	18 – 26.5	2.00	1.60	40	30	1		

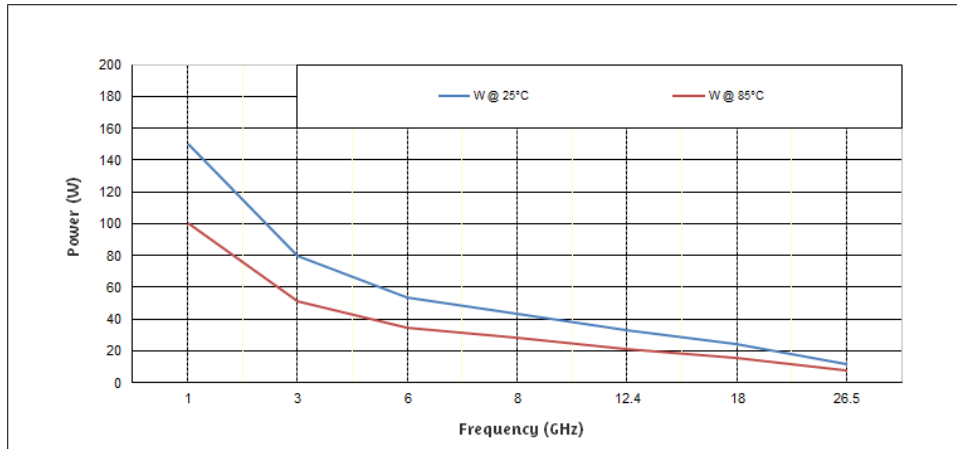
(1) : at high frequency, manual soldering may generate spikes and RF characteristics degradation, due to air gaps between PC board and relay ground.

TYPICAL RF PERFORMANCE - MEASUREMENT METHOD USING UOSM 2.92mm CALIBRATION

2.92mm UOSM calibration is performed to extract RF performances of SMT relay. **VSWR values are those of the complete evaluation board** (Relay + coaxial connectors and microstrip access lines). **Insertion loss values are those of the relay by subtracting the loss of an equivalent length of microstrip access line.**



RF POWER RATING FOR COLD SWITCHING USE



RELAY PACKAGING

For relays soldered on test fixture: individual packaging

For not soldered relays:

For quantities up to 50 relays: packaged in tape without reel

For upper quantities: packaged in tape and reel, maximum **200** relays per reel

ACCORDING TO IEC 286-3 STANDARD

**MATERIALS**

Reel : polyester

Carrier tape : PVC

Cover tape : polyester

